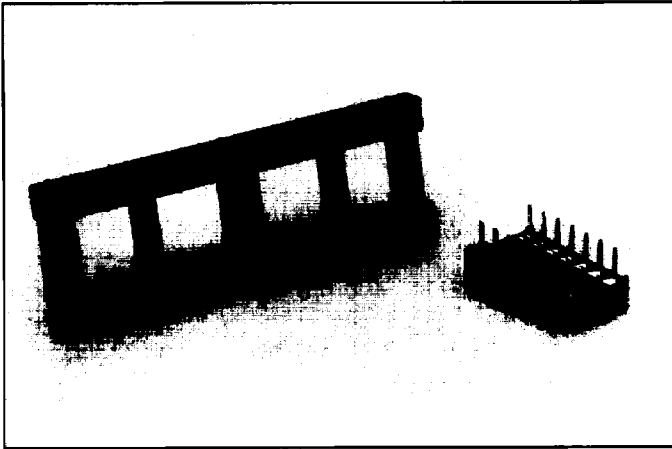


PRODUCTION DIP

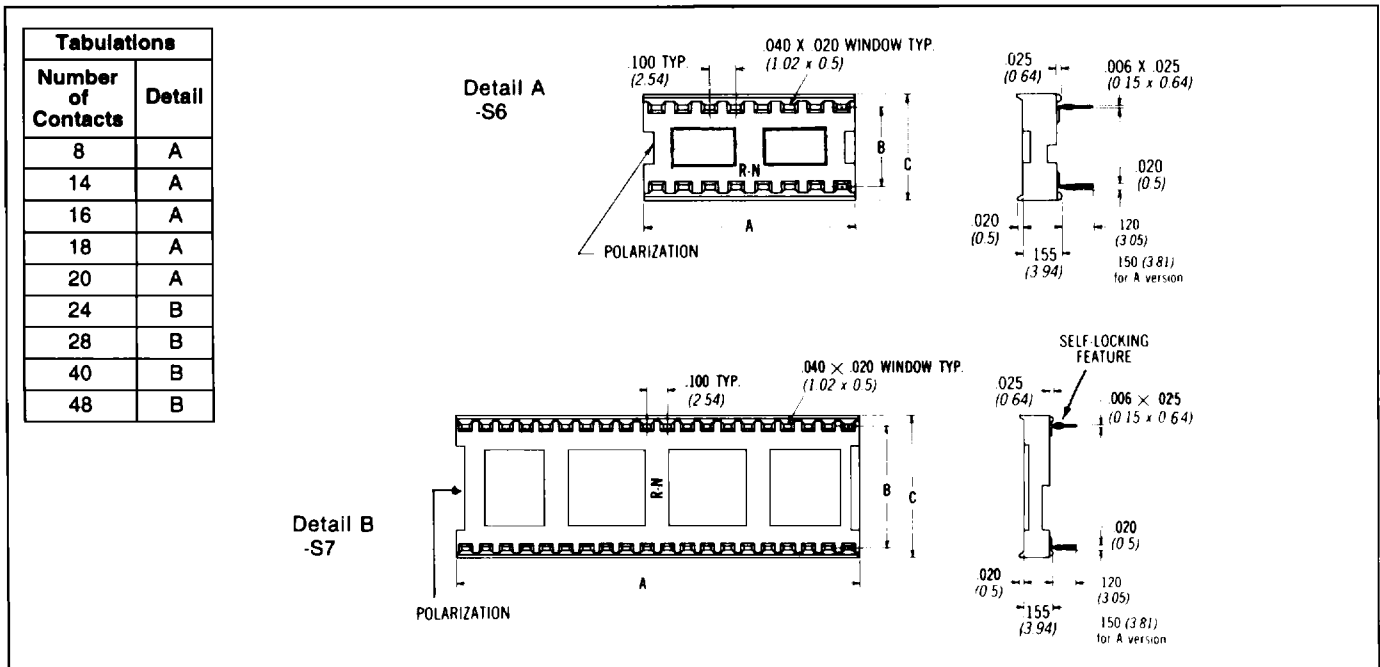


Single Wipe Sockets

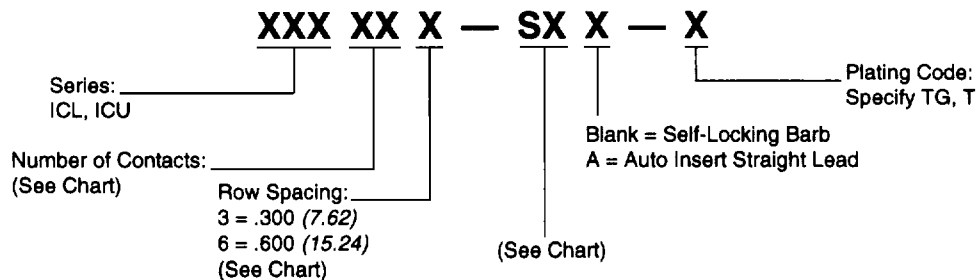
ICL/ICU Series



- High compression, single wipe contact provides high retention and gastight connections
- Automatic insertion option compatible with most insertion equipment
- Anti-overstress design prevents damage to contact spring
- Phosphor bronze option provides high reliability/low cost socket
- Side and end stackable



How To Order ICL/ICU Series



Part Numbers

Number of Contacts	Description Beryllium Copper Contacts	Description Phosphor Bronze Contacts	Dimension A	Dimension B	Dimension C
8	ICL-083-S6-T	ICU-083-S6-X	.395 (10.03)	.300 (7.62)	.395 (10.03)
14	ICL-143-S6-T	ICU-143-S6-X	.695 (17.65)	.300 (7.62)	.395 (10.03)
16	ICL-163-S6-T	ICU-163-S6-X	.795 (20.19)	.300 (7.62)	.395 (10.03)
18	ICL-183-S6-T	ICU-183-S6-X	.895 (22.73)	.300 (7.62)	.395 (10.03)
20	ICL-203-S6-T	ICU-203-S6-X	.995 (25.27)	.300 (7.62)	.395 (10.03)
24	ICL-246-S7-T	ICU-246-S7-X	1.195 (30.35)	.600 (15.24)	.695 (17.65)
28	ICL-286-S7-T	ICU-286-S7-X	1.395 (35.43)	.600 (15.24)	.695 (17.65)
40	ICL-406-S7-T	ICU-406-S7-X	1.995 (50.67)	.600 (15.24)	.695 (17.65)
48	ICL-486-S7-T	ICU-486-S7-X	2.385 (60.58)	.600 (15.24)	.695 (17.65)

Materials:

Body: Black polyester, glass-filled
 Contacts: ICL: Beryllium Copper
 ICU: Phosphor Bronze

Acceptable Pin Sizes:

Thickness: .015" (.38) maximum
 Length: .100" - .130" (2.54-3.30)

Mounting Information:

PCB Hole: .031" ± .002" (.79 ± .05)
 Location: IC and socket leads are coincident

Performance Characteristics:

Insertion Force, ICL/ICU: 6.5 oz*/contact
 Withdrawal Force, ICL: 4.5 oz*/contact
 ICU: 3.4 oz*/contact
 *Average of 2nd, 3rd, and 4th cycles using .010" flat pin.

Capacitance: 1 picofarad maximum
 Insulation Resistance: 5000 megohms minimum
 Dielectric Withstanding Voltage: 500 volts AC
 Current Rating: 1 Ampere
 Flammability: UL 94V-0
 Temperature Range:

ICL: -65°C to + 125°C
 ICU: -65°C to + 105°C

Plating Description:

Suffix: TG = 10 μinch (.254 μm) minimum Gold on contact area.
 100 μinch (2.54 μm) minimum Tin/Lead on terminal area.

ICL: T = 200 μinch (5.08 μm) minimum Tin/Lead in contact area.
 100 μinch (2.54 μm) minimum Tin/Lead on terminal area.

ICU: T = 30 μinch (.762 μm) minimum hot Tin dip and wipe

All options include: 50 μinch (1.27 μm) minimum Nickel underplate.